



Eleprint
Capability
& Design
rules



PRINTED CIRCUIT BOARDS PRODUCTION CAPABILITY

ELEPRINT 2025		
	PRODUCTION	PROTOTYPE
INNER LAYER		
Tracks	65 μm	40 μm
Insulation	65 μm	40 μm
OUTER LAYER		
Tracks	75 μm	65 μm
Insulation	75 μm	65 μm
LASER VIA PADS		
External	250 μm	230 μm
Internal	250 μm	230 μm
MECHANICAL VIA PADS		
	450 μm	400 μm
	500 μm	450 μm
ASPECT RATIO		
Laminate Thickness: Hole Diameter	1:11	1:12
SOLDER GAP		
	70 μm	50 μm

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BOARD THICKNESS

Minimum	0,100 mm
Maximum	6,000 mm

INNER LAYER LAMINATE THICKNESS

Minimum	0,050 mm
Maximum	2,400 mm

MINIMUM LINE / SPACE

Inner layer	0,050 / 0,050 mm
Outer layer	0,065 / 0,065 mm

COPPER THICKNESS

9 μm (¼ Oz)	On request, UL certified only
12 μm (⅓ Oz)	YES
17 μm (½ Oz)	YES
35 μm (1 Oz)	YES
50 μm (¾ Oz)	YES
70 μm (2 Oz)	YES
105 μm (3 Oz)	YES
> 105 μm	On request, UL certified only

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HOLE'S COPPER PLATING (nominal copper thickness)

VIA hole	$\geq 25 \mu\text{m}$
Blind VIA holes	$\leq 50 \mu\text{m}$

SBU

Standard SBU	2+N+2
Advanced SBU	3+N+3

SURFACE TREATMENT

Hot Air Levelling L.F. / SnPb [<i>HAL</i>]	1÷30 μm
Electroless Nickel Immersion Gold [<i>ENIG</i>]	Nickel 3-6 μm ; Gold 0,05÷0,07 μm
Immersion Tin [<i>Chemical Tin</i>]	1 μm typically
Hard Gold [<i>Electrolytic Gold</i>]	Nickel 4 μm ; minimum Gold 0,8÷1,2 μm
Immersion Silver [<i>Chemical Silver</i>]	0,2÷0,5 μm

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MINIMUM PAD DIAMETER

Inner layers	\emptyset hole + 250 μ m
Outers layers	\emptyset hole + 200 μ m

MINIMUM FINISHED HOLE DIAMETER

Mechanical drilled	\geq 100 μ m
Laser drilled	75 μ m \div 100 μ m

TOLERANCES

PTH holes	- 50 μ m \div + 100 μ m
PTH holes – Press Fit	- 50 μ m \div + 50 μ m
No PTH holes	\pm 50 μ m
Routing	\pm 100 μ m

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SCORING AND ROUTING

Minimum positioning tolerance	± 100 µm
Scoring Angle	30°
Tolerance to Routing/Scoring	± 200 µm
Contour Tolerance	± 100 µm
PCB Tolerance, 2 scored edges after separation	± 150 µm
Minimum distance nominal centerline to pattern / holes	500 µm
Minimum distance Routing to Pattern	Inner layers 400 µm Outers layers 200 µm

MARKING

Week Code	2 digits for weeks 2 digits for year (Eg: WW-YY)
UL Marking	UL Flammability code
Manufacturer Identification	ZPMV8.E135333 ZPMV2.E135333
Marking Sequence: <ul style="list-style-type: none"> • Eleprint manufacturer identification; • PCB Type; • UL logo. 	<p>Example:</p> 



Contacts

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